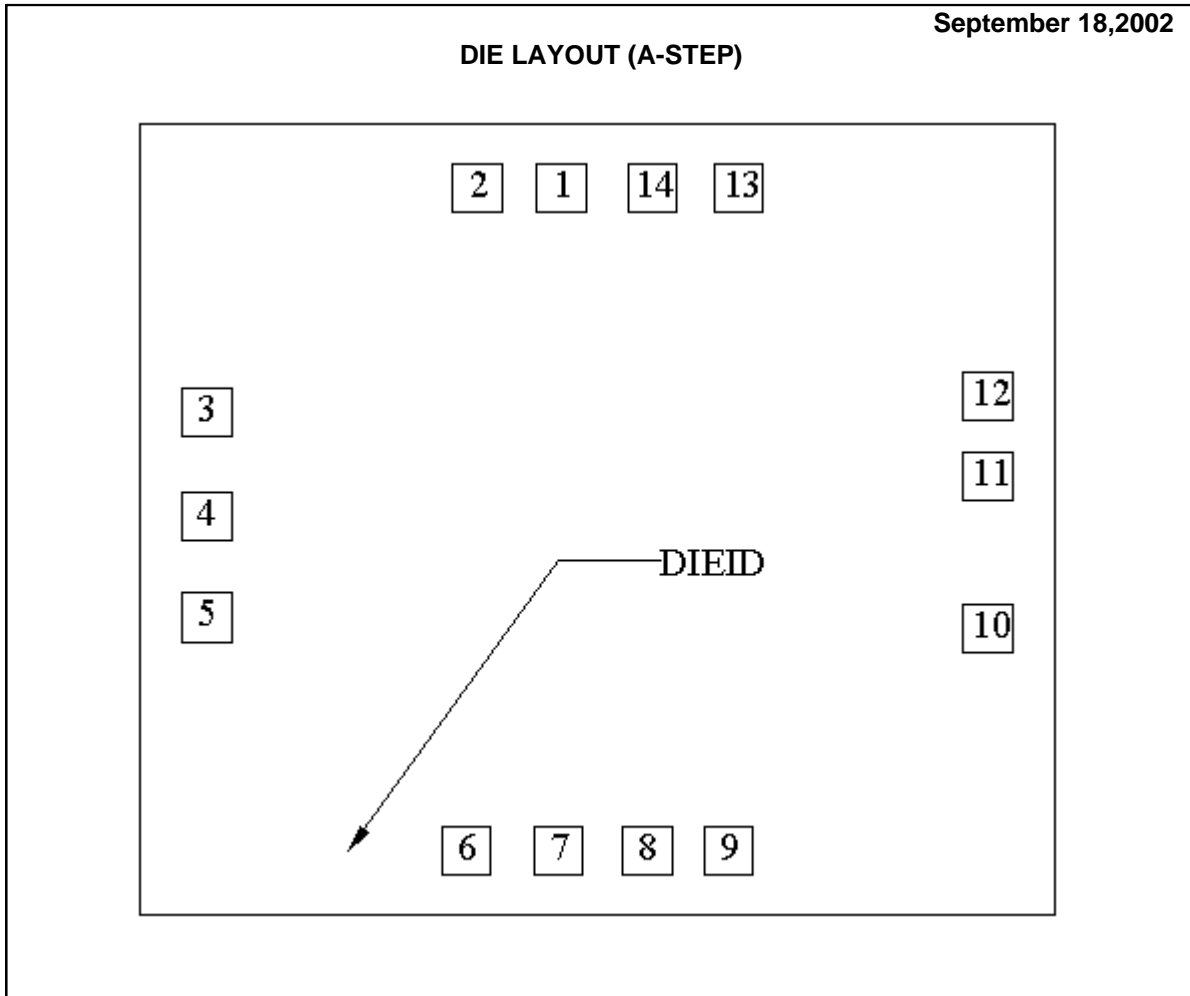


**DS90LV019 MDC MWC
3.3V OR 5V LVDS DRIVER/RECEIVER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS92LV101	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	A	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	POLYIMIDE OVER NITRIDE OVER OXIDE (TE)
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1715µm x 1486µm 68mils x 59mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	150µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES		PAD SIZE		
		X	Y	X	Y	
DE	1	-66	621	92	x	92
D _{IN}	2	-224	621	92	x	92
NC	3	-732	201	92	x	92
R _{OUT}	4	-732	5	92	x	92
NC	5	-732	-184	92	x	92
GND	6	-245	-621	92	x	92
GND	7	-73	-621	92	x	92
/RE	8	94	-621	92	x	92
RI-	9	247	-621	92	x	92
RI+	10	732	-204	92	x	92
DO-	11	732	81	92	x	92
DO+	12	732	231	92	x	92
V _{CC}	13	266	621	92	x	92
V _{CC}	14	104	621	92	x	92

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